



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: H. MAEJIMA, et al.
Serial No: 09/704,529
Filed: November 3, 2000
Title: WAFER HAVING CHAMFERED BEND PORTIONS IN THE
JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER
AND THE CUT-AWAY PORTION OF THE WAFER
Group: 2814
Examiner: L. PHAM

AMENDMENT AFTER FINAL REJECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

April 15, 2004

Sir:

The following amendments and remarks as listed below are submitted in the above-identified application in response to the final Office Action mailed January 15, 2004. A request for continued examination of the application under 37 C.F.R. §1.114 and the fee set forth in §1.17(e) are filed herewith.

Amendments to the Claims

Remarks are included following the amendments